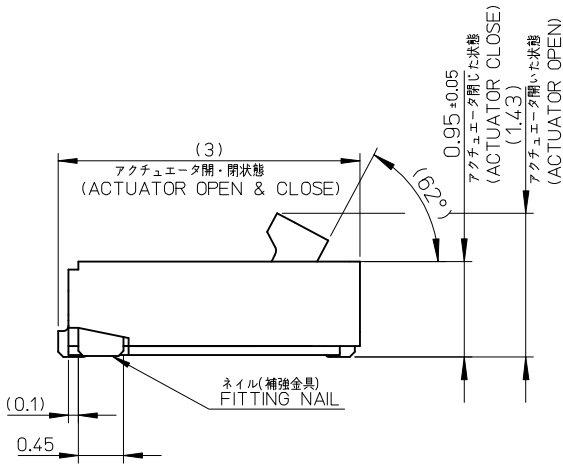
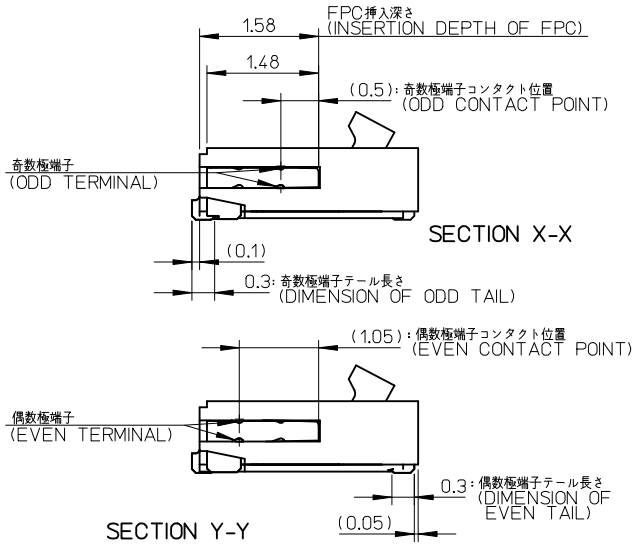


ISO VIEW (参考)



ネイルテール長さ (DIMENSION OF NAIL TAIL)

注記 NOTES:

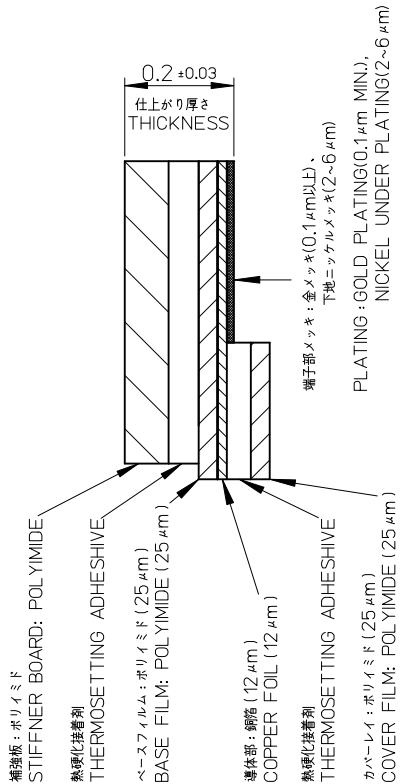
- 1.材質 MATERIAL
ハウジング:液晶ポリマー(LCP)、黒色、ガラス充填、UL94 V-0
アクチュエータ:ポリアミド樹脂(PA)、灰色、ガラス充填、UL94 HB
奇数極端子・偶数極端子:焼青銅(t=0.08)、ニッケル下地・金メッキ
ネイル(補強金具):焼青銅(t=0.12)、ニッケル下地・錫メッキ
HOUSING:LIQUID CRYSTAL POLYMER,BLACK,GLASS FILLED,UL94 V-0
ACTUATOR:POLYAMIDE,GRAY GLASS FILLED,UL94 HB
TERMINAL:PHOSPHOR BRONZE(t=0.08),GOLD OVER NICKEL PLATING
FITTING NAIL:PHOSPHOR BRONZE(t=0.12),TIN OVER NICKEL PLATING
- 2.めっき仕様 PLATING
ターミナル TERMINAL
接点部:金メッキ 0.1μm以上
テール部:金メッキ
下地:ニッケルメッキ 1.0μm以上
CONTACT AREA: GOLD PLATING 0.1μm MINIMUM
TAIL AREA: GOLD PLATING
UNDER PLATING:NICKEL PLATING 1.0μm MINIMUM
ネイル(補強金具) FITTING NAIL
錫めっき 1.0μm以上
下地:ニッケルめっき:1.0μm以上
TIN PLATING 1.0μm MINIMUM
UNDER PLATING:NICKEL PLATING 1.0μm MINIMUM
- 3.端子・ネイルの平坦度は、0.1mm以下とする。
COPLANARITY OF TAILS AND FITTING NAILS:0.1MAXIMUM.
- 4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

0.064	11.6	12.84	12.4	12	13.5	504070-6191	61
0.054	9.6	10.84	10.4	10	11.5	504070-5191	51
0.043	7.2	8.44	8	7.6	9.1	504070-3991	39
重さ (g) WEIGHT(g)	E	D	C	B	A	EMBOSSED PACKAGE オーダー番号:ORDER NO.	極数 CIRCUITS

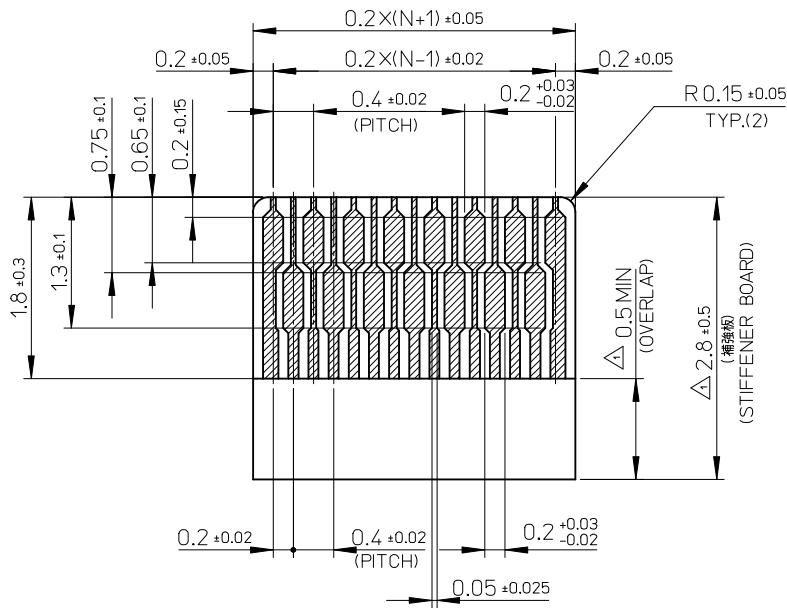
CONNECTOR SERIES NO. : 504070-***11

PROPOSED EC NO: J2013-0279 DRWN: JEBISAWA 2012/04/26 CHKD: HIJIMA 2012/06/28 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY JEBISAWA	DATE 2012/04/26	TITLE 0.2 FPC CONN. BACK FLIP HOUSING ASSY LOW-HALOGEN		
	10 OVER 30 UNDER	±0.25	CHECKED BY HIJIMA	DATE 2012/04/26	molex DOCUMENT NO. SD-504070-001 SHEET NO. 1 OF 2		
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/02/19			
REV	DESCRIPTION	ANGULAR ±1°	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
0		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3				

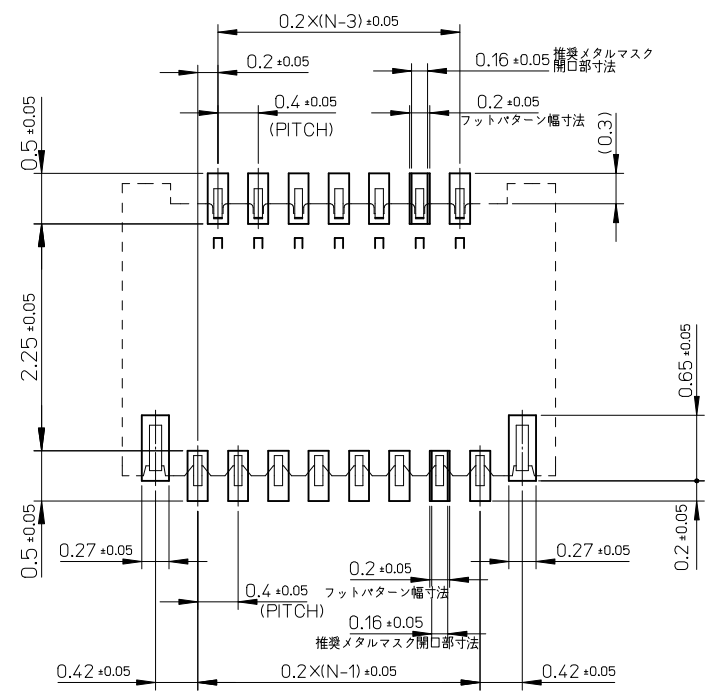
10 9 8 7 6 5 4 3 2 1



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)



推奨基板寸法
RECOMMENDED
P.C.B. PATTERN LAYOUT

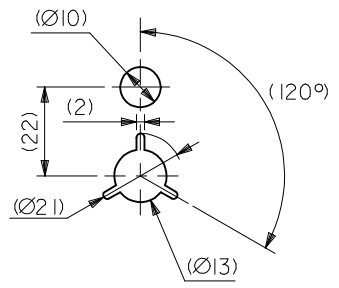
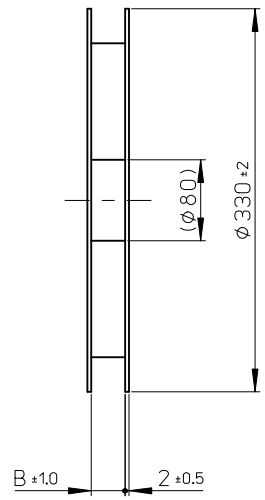
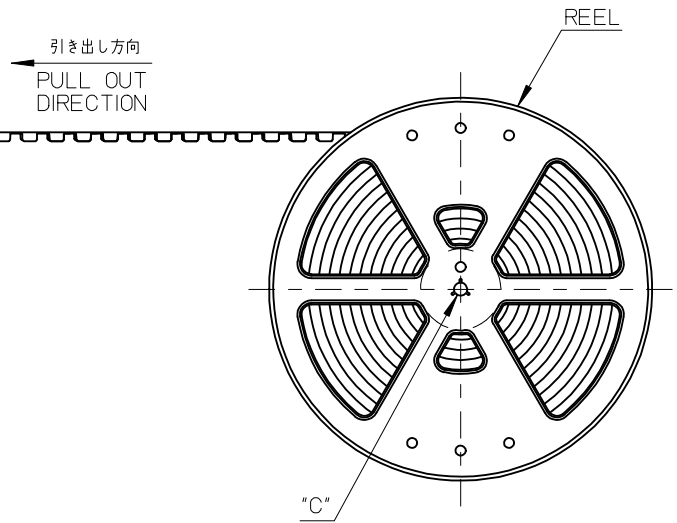
推奨ベース厚 : 100 μm
推奨マスク開口率 : 80%
RECOMMEND SCREEN THICKNESS : 100 μm
RECOMMEND SCREEN OPEN RATIO : 80%

・FPCについて(ABOUT FPC):
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL: STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

補強板長さが図面通り確保できない場合は、カバーレイと補強板のオーバーラップ寸法を0.5mm以上としてください
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

SEE SHEET 1 OF 2 EC NO: J2013-0279 DRWN: JEBISAWA 2012/04/26 CHKD: H I J I M A 2012/06/28 APPR: YNOGAWA 2014/02/19	DESCRIPTION REV 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY JEBISAWA	DATE 2012/04/26	TITLE 0.2 FPC CONN. BACK FLIP HOUSING ASSY LOW-HALOGEN			
		10 OVER 30 UNDER	± 0.25	CHECKED BY H I J I M A	DATE 2012/04/26	molex			
		30 OVER	± 0.3	APPROVED BY YNOGAWA	DATE 2014/02/19				
ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-504070-001		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

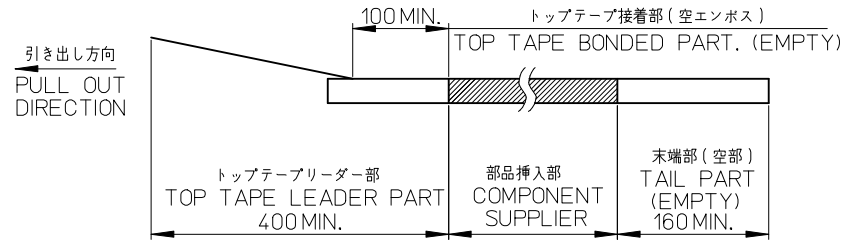
9 8 7 6 5 4 3 2



DETAIL "C"

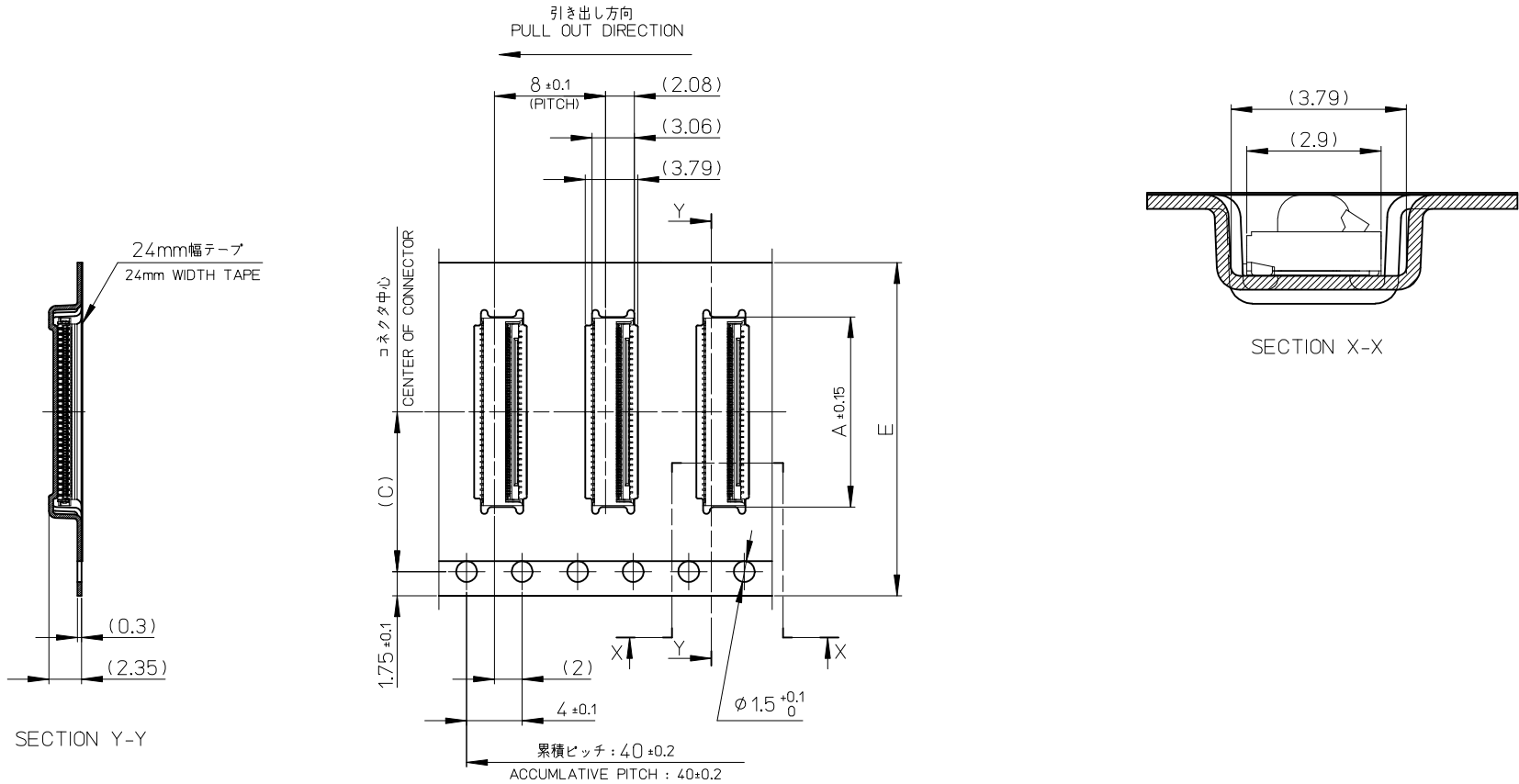
注記 NOTES

1. 製品詳細寸法については図面 RSD-504070-001 を参照下さい。
REFER TO THE RSD-504070-001 ABOUT DIMENSIONS IN DETAIL.
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS：3000 PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. 材料 MATERIAL
 キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYRENE)
 トップテープ (TOP TAPE)：PET, PE, PEF
 リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>
 POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
5. ELV 及び RoHS 適合品
 ELV AND ROHS COMPLIANT

PROPOSED EC NO: J2013-0279 DRWN: TUEDA 2014/02/03 CHKD: HIJIMA 2014/02/04 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY TUEDA	DATE 2014/02/03	TITLE 0.2 FPC CONN. BACK FLIP TAPING PACKAGE (504070-**11 SERIES)	
	10 OVER 30 UNDER	± ---	CHECKED BY HIJIMA	DATE 2014/02/04		
	30 OVER	± ---	APPROVED BY YNOGAWA	DATE 2014/02/19		
ANGULAR ±1 °		MATERIAL NO. SEE CHART	DOCUMENT NO. SD-504070-002	SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



24±0.3	11.5	25.4	13.7	504070-6191	61
			11.7	504070-5191	51
			9.3	504070-3991	39
E キャリアテープ幅 EMBOSSED TAPE WIDTH	C	B	A	オーダー番号 ORDER NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO.: J2013-0279 DRWN: TUEDA 2014/02/03 CHKD: HIJIMA 2014/02/04 APPR: YNOGAWA 2014/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	± ---	TUEDA	2014/02/03	0.2 FPC CONN. BACK FLIP TAPING PACKAGE (504070-**11 SERIES)					
	30 OVER	± ---	CHECKED BY	DATE						
	ANGULAR	± 1 °	HIJIMA	2014/02/03						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		YNOGAWA	2014/02/19	SEE CHART		SD-504070-002		2 OF 2		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								